ASSOCIATION CONNE ELECTRONICS INDUS	Material Composition © Copyright 2005. IPC, international and Pan-Ar	Bannockb	urn, Illinois. A	Il rights reserved untions.	nder both	This docum level parts, t	ent is a declaration	ion of the s encompasse	ubstances es all lower	within the manufactur r level materials for w	rer listed	item. Note: i nanufacturer	f the item is an as r has engineering	ssembly with lower responsibility.	
1752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				*	* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials a					s and Mfg Information				
Supplier Info	ormation														
Company name	ý*	Company unique ID				Unique ID Authority				Response Date*					
onsemi											2024-04	2024-04-26			
Contact Name		Title - Contact				Phone - Contact*				Email -	Email - Contact*				
Product-Env-St	tewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com					
Authorized Rep	presentative*	Title - Representative				Phone - Representative*				Email - Representative*					
Product-Env-St	tewards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
Requ	Requester Item Number Mfr Item		n Number Mfr Item Name				Effective Date	e Date Version Manufacturing Site			Weight*	UOM	Unit Type		
		ECH8654-TL-H PCH+PCH 1.8V DI		DRIVE SERIE	S	2024-04-26 CNG		CNG		19.18	mg	Each			
Manufacturi	ing Proccess Information	n													
Term	Terminal Plating / Grid Array Material Term			erminal Base Alloy J-STD-020 MSL			Peak Process Body Temperature Max Time at Peak				Temperature Number of Reflow Cycles				
contains Bi CU Alloy			CU Alloy		1		260		С	30	seco	nds 3			
Comments															
level 1 - maximu	um time at peak temperature o	during sol	dering is 10-3	0 seconds											
For more inform	mation regarding material con	position j	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	(Pb), Mercury (Hg), Hexavalent Chro	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company that agreement, will be the sole and exclusive	Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, admium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part ontains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall ncompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, so fithe date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on informationprovided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not ndependently verified information provided by others, Supplier agrees that, at a minimum, itsuppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the ertification in this paragraph. If the Company and the Supplier remedies provided as part of heat agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the varranty rights and/or remedies of Supplier's Standard Terms andConditions of Sale applicable											
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted							
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).									
Exemption List Version	EL-2011/534/EU											
Declaration Signature												
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the							
Supplier Digital Signature	astislav Drska	Le										

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	1.32	mg	Supplier	Silicon (Si)	7440-21-3		1.32	mg
Die Attach Solder	1.18	mg	Supplier	Silver (Ag)	7440-22-4		0.0295	mg
			А	Lead (Pb)	7439-92-1	7a	1.0915	mg
			Supplier	Tin (Sn)	7440-31-5		0.059	mg
Lead Frame	8.66	mg	Supplier	Silver (Ag)	7440-22-4		0.1048	mg
			Supplier	Tin (Sn)	7440-31-5		0.0121	mg
			Supplier	Copper (Cu)	7440-50-8		8.5431	mg
Mold Compound-Black	7.87	mg		Epoxy Phenol Resin	proprietary data		0.2991	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0787	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		0.787	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		5.509	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2		1.1805	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		0.0157	mg
Plating	0.14	mg	В	Bismuth (Bi)	7440-69-9		0.0008	mg
			Supplier	Tin (Sn)	7440-31-5		0.1392	mg
Wire Bond - Au	0.01	mg	Supplier	Gold (Au)	7440-57-5		0.01	mg

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).